

ABSTRACT

TESTING OF BGA AND OTHER CSP PACKAGES USING PROBING TECHNIQUES

A method and apparatus for handling small semiconductor devices in the testing of these devices. Multiple devices are mounted within a device strip carrier and are positioned in the testing position. This positioning of the device strip carriers is performed using device strip carrier alignment tools; the device strip carrier can readily be repositioned with respect to the test head/probe card for testing of multiple devices contained within the device strip carrier.

(FIGURE 1A IS SUGGESTED FOR PUBLICATION)